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VER SHEET

U.S. DEPARTMENT OF COMMERCE

09/889694

Patent and Trademark Office

OHS-303

C17 Rec'd PCT/PTO

20 JUL 2001

ereof.

1. Name of conveying party(ies):

Hitoshi ANABUKI
Machiko YOKOZEKI

07/20/01

2. Name and address of receiving party(ies):

Name: Kyowa Chemical Industry Co., Ltd.

Internal Address:

Additional name(s) of conveying party(ies)
attached? ☐ Yes ☒ No

3. Nature of Conveyance

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: July 9, 2001Street Address: 305, YashimanishimachiTakamatsu-shiCity: Kagawa State: Japan ZIP: 761-0113Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

09/889694

If this document is being filed together with a new application, the execution date
of the application is: July 9, 2001

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: SHERMAN & SHALLOWAY

Internal Address:

07/24/2001 FAX/PAGE 00000075 09089694

03 FC:581

40.00 DP

Street Address: _____

413 North Washington StreetCity: Alexandria State: VAZIP: 22314

6. Total number of applications and patents involved:..... [1]

7. Total fee (37 CFR 3.41).....\$40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying
by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any
attached copy is a true copy of the original document

Leonard W. Sherman

Name of Person Signing

Signature

July 20, 2001

Date

Total number of pages including cover sheet, attachments, and document [2]

A S S I G N M E N TWHEREAS, We, Hitoshi ANABUKI and Machiko YOKOZEKIresiding at Sakaide-shi, KAGAWA, JAPAN(hereinafter referred to as Inventors), have invented certain new and useful improvements in RESIN COMPOSITION, MOLDED PRODUCTS FORMED THEREFROM AND USE THEREOFfor which an application for United States Letters Patent was signed by us on July 9, 2001 and filed in the United States on _____ and assigned Serial Number _____.

WHEREAS, KYOWA CHEMICAL INDUSTRY CO., LTD.
 a corporation of Japan, having a place of business at 305, Yashimanishimachi, Takamatsu-shi, KAGAWA 761-0113 JAPAN (hereinafter referred to as Company), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Company, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Company as the assignee of the entire right, title and interest in and to the same, for the sole use and behoof of the said Company, its successors and assigns.

FURTHER, We agree that we will communicate to said Company or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Company, make all rightful oaths and generally do everything possible to aid said Company, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, We have hereunto set our hands this 9th day of July, 2001.

Signed in the presence of:

Witness: Keiko Kato Signed: Hitoshi AnabukiWitness: _____ Signed: Machiko Yokozeki

Witness: _____ Signed: _____

Witness: _____ Signed: _____

Witness: _____ Signed: _____

Witness: _____ Signed: _____

PATENT**RECORDED: 08/20/2001****REEL: 012123 FRAME: 0386**